

In the paragraph from page 10, line 20 to page 11, line 2:

After the TiN layer 31 is formed as the glue layer, the first and second contact holes 29a and 29b are filled in with tungsten. As shown in FIG. 4, a tungsten layer 33 is deposited over the second interlayer dielectric layer 27, including over the contact holes 29a and 29b, so that the contact holes 29a and 29b are completely filled with the tungsten layer 33. The method may include a plasma treatment that is further performed during the deposition of the CVD TiN layer while using N<sub>2</sub> and H<sub>2</sub> gas either together or alone, or alternatively, is performed after the deposition of the CVD TiN layer.

**IN THE CLAIMS:**

Please replace Claims 1, 4-5, 10, and 13-14 with the following amended Claims 1, 4-5, 10, and 13-14 amended in accordance with the revised format. The text of all pending claims is also set forth.